

Phase Change Materials

Product Name	Description	Key Attributes	Thermal Conductivity (W/m•K)	Phase Change Temperature (°C)	Dielectric Strength (V/25 µm)	Thickness (mm)	Flammability Rating
Aluminum Carrier							
BERGQUIST HI-FLOW 225F-AC	Phase change thermal interface material	 Low thermal impedance Can be manually or automatically applied to the surfaces of room-temperature heat sinks Foil reinforced, adhesive coated Soft phase change compound 	1	55	N/A	• 0.102	UL 94 V-0
LOCTITE TCF 1000	Non-insulating, phase change thermal interface material	 Low thermal impedance Coated on aluminum foil Used between any non-isolated heat dissipating component and a heat sink or chassis 	1	60	N/A	• 0.06 - 0.2	None
LOCTITE TCF 2000	Non-insulating, phase change thermal interface material	 Used between any non-isolated heat dissipating component and a heat sink or chassis High thermal conductivity 	3	51	N/A	• 0.076	UL 94 V-0
Polyimide Carrier							
LOCTITE EIF 1000	High-performance, phase change thermal Interface material	High dielectric strengthExcellent cut-through resistance	0.45	60	> 5,000	• 0.05 - 0.2	UL 94 V-0
BERGQUIST HI-FLOW 300P	High-performance, phase change thermal interface material	 Field-proven polyimide film Excellent dielectric performance Excellent cut-through resistance Outstanding thermal performance in an insulated pad 	1.6	55	5,000	• 0.102 - 0.127	UL 94 V-0
No Carrier							
BERGQUIST HI-FLOW 565UT	High-performance, phase change thermal interface material	 Very low thermal impedance High thermal conductivity Naturally tacky Tabulated for ease of assembly 	3	52	N/A	• 0.127 • 0.254	UL 94 V-0

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